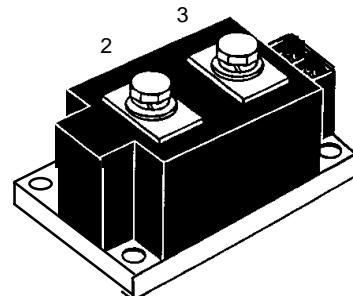
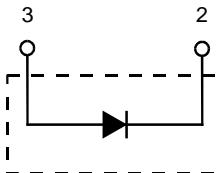


High Power Diode Modules

I_{FRMS} = 880 A
I_{FAVM} = 560 A
V_{RRM} = 1200-2200 V

V _{RSM} V _{DSM} V	V _{RRM} V _{DRM} V	Type
1300	1200	MDO 500-12N1
1500	1400	MDO 500-14N1
1700	1600	MDO 500-16N1
1900	1800	MDO 500-18N1
2100	2000	MDO 500-20N1
2300	2200	MDO 500-22N1



Symbol	Test Conditions	Maximum Ratings		
I _{FRMS}	T _{VJ} = T _{VJM}	880	A	
I _{FAVM}	T _C = 85°C; 180° sine	560	A	
I _{FSM}	T _{VJ} = 45°C V _R = 0	t = 10 ms (50 Hz) t = 8.3 ms (60 Hz)	15000 16000	A A
	T _{VJ} = T _{VJM} V _R = 0	t = 10 ms (50 Hz) t = 8.3 ms (60 Hz)	13000 14400	A A
I ² t	T _{VJ} = 45°C V _R = 0	t = 10 ms (50 Hz) t = 8.3 ms (60 Hz)	1125000 1062000	A ² s A ² s
	T _{VJ} = T _{VJM} V _R = 0	t = 10 ms (50 Hz) t = 8.3 ms (60 Hz)	845000 813000	A ² s A ² s
T _{VJ}			-40...140	°C
T _{VJM}			140	°C
T _{stg}			-40...125	°C
V _{ISOL}	50/60 Hz, RMS	t = 1 min	3000	V~
	I _{ISOL} ≤ 1 mA	t = 1 s	3600	V~
M _d	Mounting torque (M6)	4.5-7/40-62	Nm/lb.in.	
	Terminal connection torque (M8)	11-13/97-115	Nm/lb.in.	
Weight	Typical including screws	650	g	

Symbol	Test Conditions	Characteristic Values		
I _{RRM}	T _{VJ} = T _{VJM} ; V _R = V _{RRM}	30	mA	
V _F	I _F = 1200 A; T _{VJ} = 25°C	1.3	V	
V _{To}	For power-loss calculations only (T _{VJ} = T _{VJM})	0.8	V	
r _T		0.38	mΩ	
R _{thJC}	DC current	0.072	K/W	
R _{thJK}	DC current	0.096	K/W	
d _s	Creeping distance on surface	21.7	mm	
d _A	Creepage distance in air	9.6	mm	
a	Maximum allowable acceleration	50	m/s ²	

Data according to IEC 60747 and refer to a single diode unless otherwise stated.
IXYS reserves the right to change limits, test conditions and dimensions

Features

- International standard package
- Direct copper bonded Al₂O₃-ceramic with copper base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered E 72873

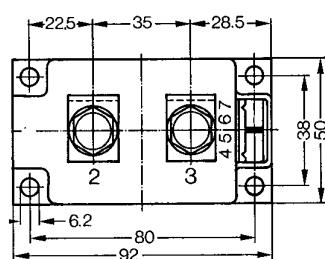
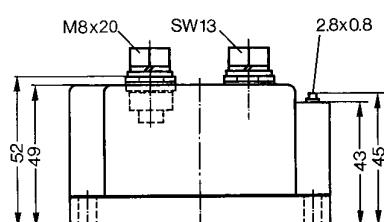
Applications

- Supplies for DC power equipment
- DC supply for PWM inverter
- Field supply for DC motors
- Battery DC power supplies

Advantages

- Simple mounting
- Improved temperature and power cycling
- Reduced protection circuits

Dimensions in mm (1 mm = 0.0394")



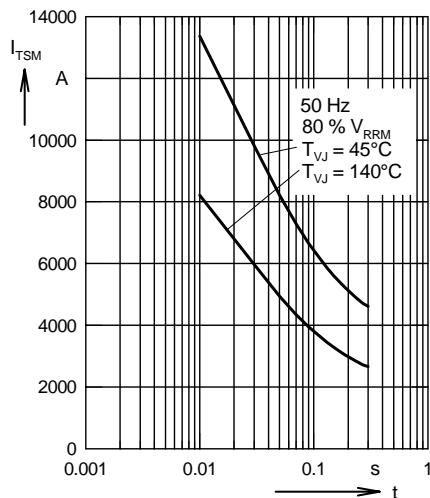


Fig. 1 Surge overload current
 I_{TSM} : Crest value, t : duration

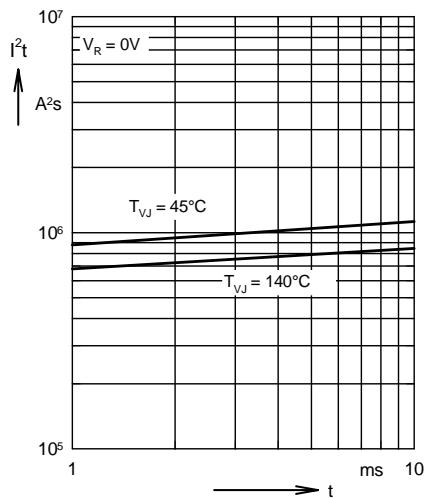


Fig. 2 I^2t versus time (1-10 ms)

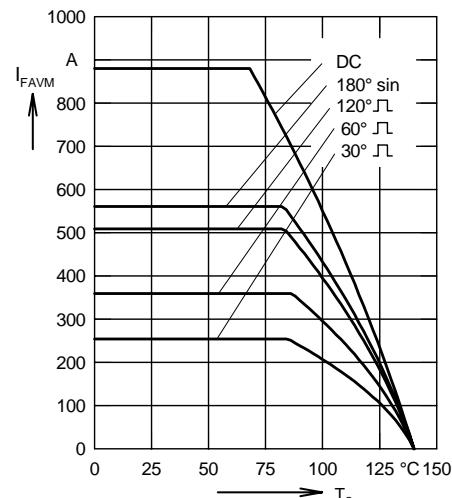


Fig. 3 Maximum forward current at case temperature

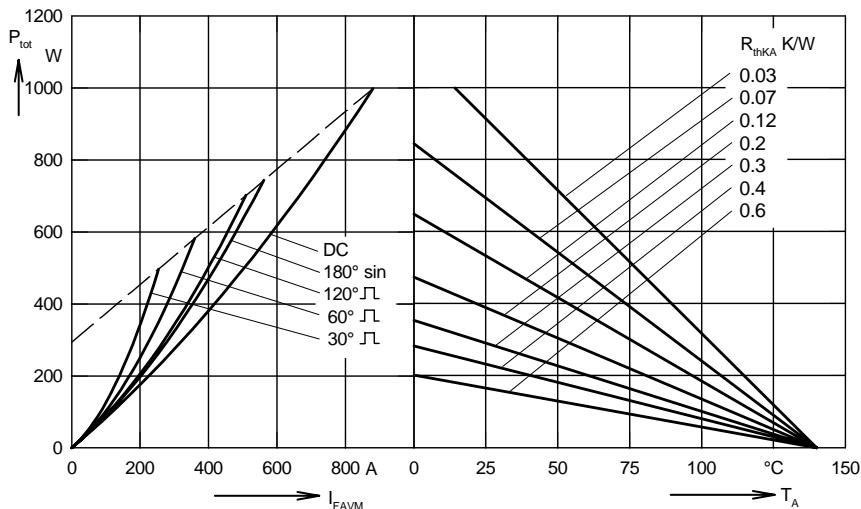


Fig. 4 Power dissipation versus forward current and ambient temperature

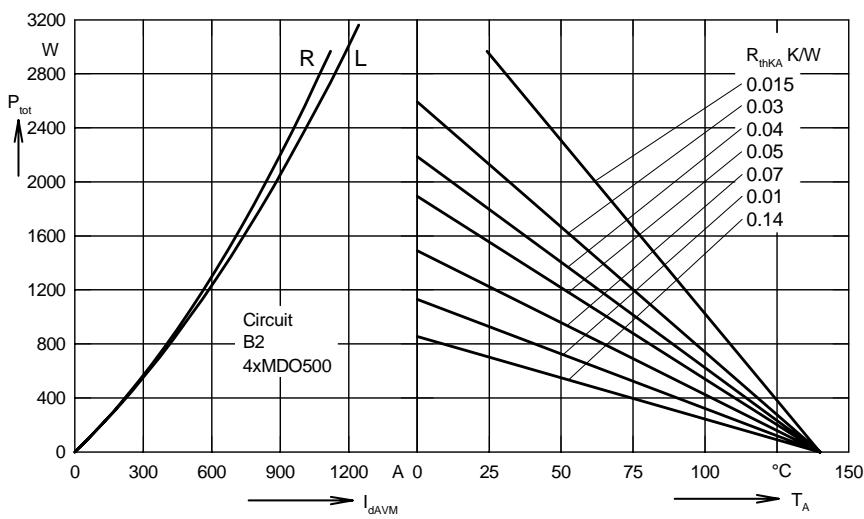


Fig. 5 Single phase rectifier bridge:
Power dissipation versus direct output current and ambient temperature
R = resistive load
L = inductive load

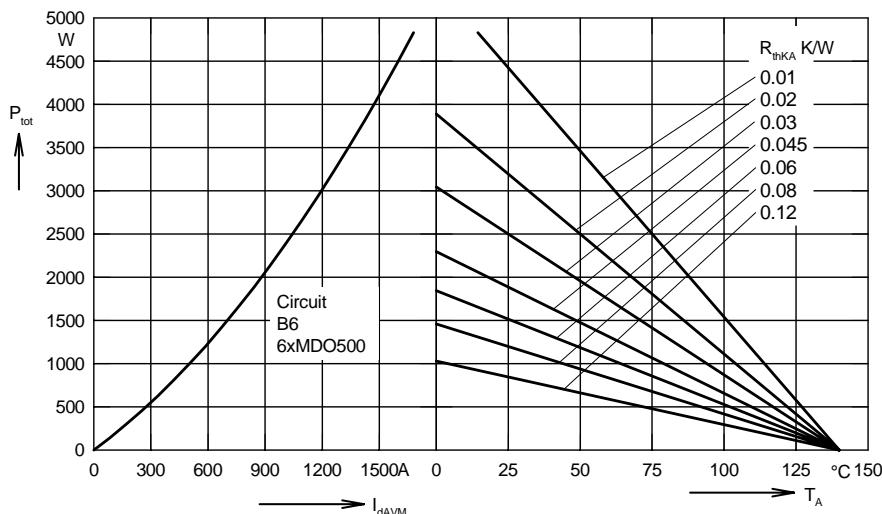


Fig. 6 Three phase rectifier bridge:
Power dissipation versus direct
output current and ambient
temperature

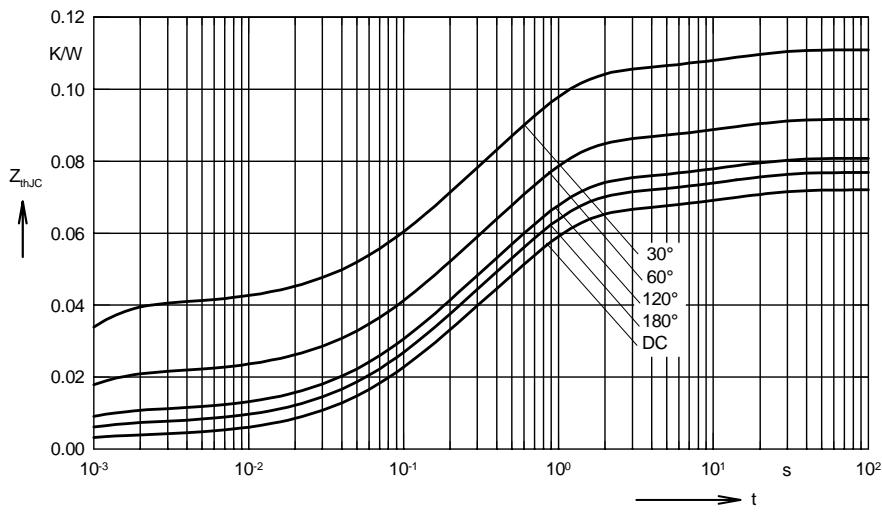


Fig. 7 Transient thermal impedance
junction to case

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.072
180°	0.0768
120°	0.081
60°	0.092
30°	0.111

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.0054
2	0.0186	0.098
3	0.0432	0.54
4	0.0067	12

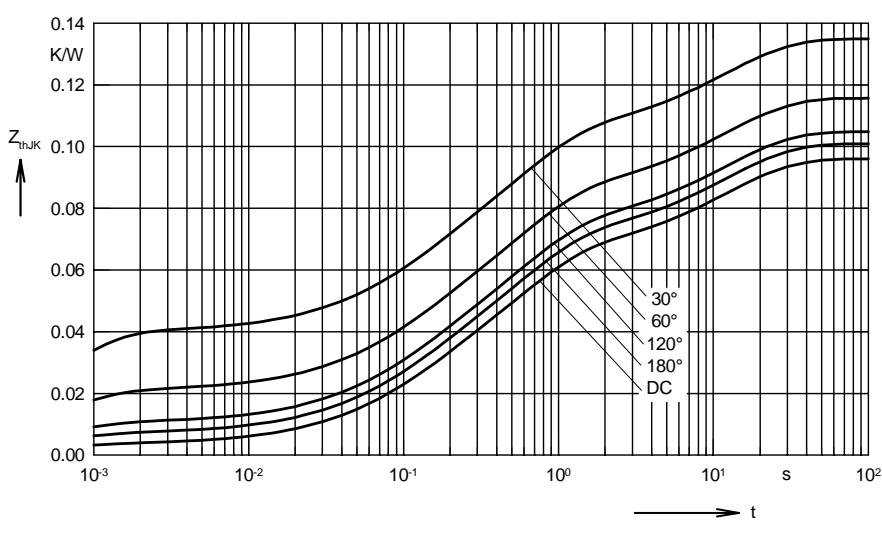


Fig. 8 Transient thermal impedance
junction to heatsink

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.096
180°	0.1
120°	0.105
60°	0.116
30°	0.135

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.0054
2	0.0186	0.098
3	0.0432	0.54
4	0.0067	12
5	0.024	12